

Printed board assemblies - Part 2: Sectional
specification - Requirements for surface mount
soldered assemblies

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

See Eesti standard EVS-EN 61191-2:2017 sisaldab Euroopa standardi EN 61191-2:2017 ingliskeelset teksti.	This Estonian standard EVS-EN 61191-2:2017 consists of the English text of the European standard EN 61191-2:2017.
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English Version

**Printed board assemblies - Part 2: Sectional specification -
Requirements for surface mount soldered assemblies
(IEC 61191-2:2017)**

Ensembles de cartes imprimées - Partie 2: Spécification
intermédiaire - Exigences relatives à l'assemblage par
brasage pour montage en surface
(IEC 61191-2:2017)

Elektronikaufbauten auf Leiterplatten -
Teil 2: Rahmenspezifikation - Anforderungen an gelötete
Baugruppen in Oberflächenmontage
(IEC 61191-2:2017)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

The text of document 91/1386/CDV, future edition 3 of IEC 61191-2, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61191-2:2017.

The following dates are fixed:

- latest date by which the document has to be (dop) 2018-04-13
implemented at national level by
publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2020-10-13
standards conflicting with the
document have to be withdrawn

This document supersedes EN 61191-2:2013.

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Endorsement notice

The text of the International Standard IEC 61191-2:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-20	NOTE	Harmonized as EN 60068-2-20.
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58.
IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1.
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2.
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3.
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4.
IEC 61188-5-5	NOTE	Harmonized as EN 61188-5-5.
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-6.
IEC 61188-7	NOTE	Harmonized as EN 61188-7.
IEC 61189-2	NOTE	Harmonized as EN 61189-2.
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2.
IEC 61193-1	NOTE	Harmonized as EN 61193-1.
IEC 61193-3	NOTE	Harmonized as EN 61193-3.
IEC 62326-1	NOTE	Harmonized as EN 62326-1.
IEC 62326-4	NOTE	Harmonized as EN 62326-4.
IEC 62326-4-1	NOTE	Harmonized as EN 62326-4-1.
ISO 9001	NOTE	Harmonized as EN ISO 9001.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61191-1	-	Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN 61191-1	-
IPC-A-610	-	Acceptability of Electronics Assemblies	-	-

CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	7
3 Terms and definitions	7
4 General requirements	7
5 Surface mounting of components.....	7
5.1 General.....	7
5.2 Alignment requirements	8
5.3 Process control.....	8
5.4 Surface mounted component requirements	8
5.5 Flatpack lead forming.....	8
5.5.1 General	8
5.5.2 Surface mounted device lead bends	8
5.5.3 Surface mounted device lead deformation	9
5.5.4 Flattened leads.....	9
5.5.5 Dual-in-line packages (DIPs)	9
5.5.6 Parts not configured for surface mounting.....	9
5.6 Small devices with two terminations	9
5.6.1 General	9
5.6.2 Stack mounting.....	9
5.6.3 Devices with external deposited elements.....	9
5.7 Lead component body positioning	10
5.7.1 General	10
5.7.2 Axial-leaded components.....	10
5.7.3 Other components	10
5.8 Parts configured for butt lead mounting.....	10
5.9 Non-conductive adhesive coverage limits.....	10
6 Acceptance requirements	10
6.1 General.....	10
6.2 Control and corrective actions.....	10
6.3 Surface soldering of leads and terminations.....	11
6.3.1 General	11
6.3.2 Solder fillet height and heel fillets	11
6.3.3 Flat ribbon L and gull-wing leads	12
6.3.4 Round or flattened (coined) leads	13
6.3.5 J leads.....	14
6.3.6 Rectangular or square end component	15
6.3.7 Cylindrical end-cap terminations	16
6.3.8 Bottom only terminations	17
6.3.9 Castellated terminations	18
6.3.10 Butt joints	19
6.3.11 Inward L-shaped ribbon leads.....	20
6.3.12 Flat lug leads.....	21
6.3.13 Ball grid array.....	22
6.3.14 Column grid array.....	23
6.3.15 Bottom termination components.....	24

6.3.16	Components with bottom thermal plane terminations (D-Pak)	24
6.3.17	P-style terminations	26
6.4	General post-soldering requirements applicable to all surface-mounted assemblies	26
6.4.1	Dewetting	26
6.4.2	Leaching	26
6.4.3	Pits, voids, blowholes, and cavities	26
6.4.4	Solder wicking	27
6.4.5	Solder webs and skins	27
6.4.6	Bridging	27
6.4.7	Degradation of marking	27
6.4.8	Solder spikes	27
6.4.9	Disturbed joint	27
6.4.10	Component damage	27
6.4.11	Open circuit, non-wetting	27
6.4.12	Component tilting	27
6.4.13	Non-conducting adhesive encroachment	28
6.4.14	Open circuit, no solder available	28
6.4.15	Component on edge	28
7	Rework and repair	28
Annex A	(normative) Placement requirements for surface mounted devices	30
A.1	General	30
A.2	Component positioning	30
A.3	Small devices incorporating two terminations	30
A.3.1	Metallization coverage over the land (side-to-side)	30
A.3.2	Metallization coverage over the land (end)	30
A.4	Mounting of cylindrical end-cap devices (MELFs)	30
A.5	Registration of castellated chip carriers	30
A.6	Surface mounted device lead and land contact	30
A.7	Surface mounted device lead side overhang	30
A.8	Surface mounted device lead toe overhang	31
A.9	Surface mounted device lead height off land (prior to soldering)	31
A.10	Positioning of J lead devices	31
A.11	Positioning gull-wing lead devices	31
A.12	External connections to packaging and interconnect structures	31
Bibliography		32
Figure 1	– Lead formation for surface mounted device	8
Figure 2	– Fillet height	12
Figure 3	– Flat ribbon and gull-wing leads	13
Figure 4	– Round or flattened (coined) lead joint	14
Figure 5	– J lead joint	15
Figure 6	– Rectangular or square end components	16
Figure 7	– Cylindrical end-cap terminations	17
Figure 8	– Bottom only terminations	18
Figure 9	– Leadless chip carriers with castellated terminations	19
Figure 10	– Butt joints	20

Figure 11 – Inward L-shaped ribbon leads	21
Figure 12 – Flat lug leads	22
Figure 13 – BGA with collapsing balls	23
Figure 14 – Bottom termination components	24
Figure 15 – Bottom thermal plane terminations	25
Figure 16 – P-style terminations	26
Table 1 – BGA with non-collapsing balls	23
Table 2 – Column grid array.....	23
Table 3 – Reworkable defects	29

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